



# AGIPD 1.0

## Tests & Plans

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# AGIPD 1.0 Functional Testing



	Satus	Results
Interface	works	works
Memory Addressing	works	works
Readout	works	last data pulse possibly truncated (can be overcome by firmware)
Readout	works	different speeds on ports (under investigation)
Noise	ongoing	~260e RMS
Dynamic Range	ongoing	calibration required





# AGIPD 1.0 Documentation

The AGIPD 1.0 Manual (~180 pages!) is available at:  
[http://www.desy.de/~trunk/AGIPD10\\_Manual.pdf](http://www.desy.de/~trunk/AGIPD10_Manual.pdf)

## The AGIPD 1.0 ASIC Manual

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### Abstract

This document describes the AGIPD 1.0<sup>1</sup> ASIC<sup>2</sup> in terms of geometry, port definitions, electrical specifications, and of the implemented communications protocol. It furthermore provides brief descriptions of circuits implemented and sample command sequences for the operation of the ASIC.

AGIPD 1.0 is the circuit to read out the AGIPD detector for the European XFEL. The detector features 1M (1024 × 1024) pixels of 200µm pitch and is constructed from sensors of 128 × 512 pixels, bump-bonded to 2 × 8 ASICs. Each ASIC consists of the readout electronics for 64 × 64 pixels:

- A charge sensitive preamplifier with 3-fold self-adapting gain in each pixel
- A correlated double-sampling stage in each pixel
- Analogue storage for 352 samples (images) in each pixel
- Amplifiers and multiplexers to readout these signals via 4 differential analogue outputs
- Circuits for biasing and test signal injection
- A tree-line serial interface to receive commands and digital circuitry to decode these and to steer and control the circuits mentioned above.

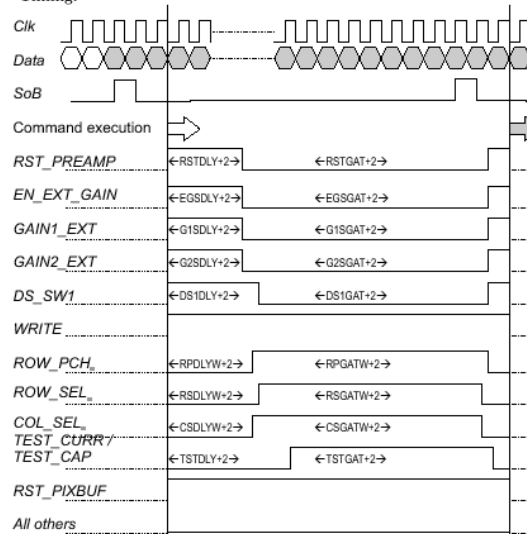
<sup>1</sup>Adaptive Gain Integrating Pixel Detector  
<sup>2</sup>Application Specific Integrated Circuit

## ACQMEM

**Description:** Acquire an image and store it at memory address  $M$ .

**Format:** 100001AAAAAAAAA with  $A = AAAAAAAAA$  representing the 9-bit memory address. Addresses with  $A > 351$  ( $A > 101011111$ ) are ignored.

### Timing:



### Dependencies:

Depends upon:  
SETUPR, RSDLYW, RSGATW, RPDLYW, RPGATW, CSDLYW, CSGATW, DS1DLY, DS1GAT, RSTDLY, RSTGAT, G1SDLY, G1SGAT, G2SDLY, G2SGAT, EGSPLY, EGSAT

Via SETUPR the following dependencies can be introduced:  
TSTDLY, TSTGAT, TIROWN, TICOLM

### Influences:

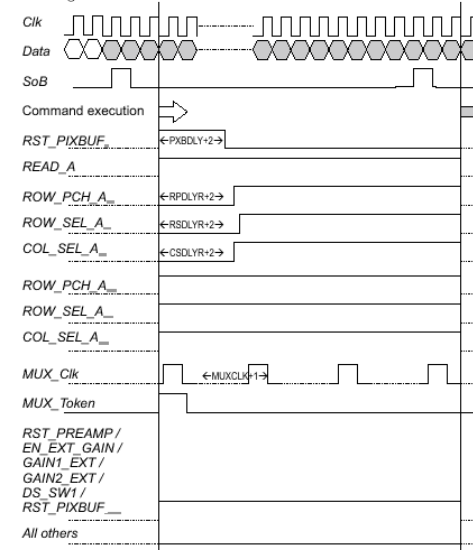
RPAMPN, RPAMPA, RPNMFA, RPDMPN, RPDMPD, RPNMPD

## RPAMPA<sup>11</sup>

**Description:** (Pre-)Read analogue data at memory address  $A$  from pixel row  $P$  and assert it to the column bus. Data from pixel row  $M$  is multiplexed from the column bus to the outside. This data has to be asserted to the column bus in the immediately preceding command (i.e.  $M$  had to be the  $A$ -argument of the immediately preceding RPAMPN or RPAMPA command). Since all even pixel rows connect to one and all odd pixel rows to the other column bus, the pixel row addresses  $A$  and  $P$  must differ in their LSB, otherwise err is set and the command will not perform as expected. It is in the responsibility of the programmer, to ensure that the command duration (in terms of Clk-cycles) is greater or equal to  $16 \times (\text{MUXCLK} + 1)$  to prevent corruption of the read out data.

**Format:** 1011PPPPPPMMMM with  $P = PPPPPP$  and  $M = MMMMM$  representing the 6-bit pixel row address to be read from the pixel and to be multiplexed off-chip.

### Timing:



### Dependencies:

Depends upon:  
SETMEN or ACQMEM, RSDLYR, RPDLYR, CSDLYR, MUXCLK

<sup>11</sup>RPAMPA is an acronym for Read Pixel Analogue, MultiPlex out Analogue





- define bias points
- identify a “Golden Device”
  - Produce o(5) boards with chips from different sites on wafer
- measure dynamic range
  - with pulsed capacitor and laser
- access nonlinearity
  - @ first point after gain switching
  - @ end of dynamic range
    - crosscheck with AGIPD 0.5
    - investigate suitable fits (3<sup>rd</sup> order polynomial?)
    - investigate possible reasons
      - diode bias?
- Identify cause for different speeds on different outputs/ADCs
  - speed map
  - investigate ADCs/buffers on chiptester box
- Define and implement an algorithm for wafer-testing